

General Description

The MX7533 is a low cost CMOS 4-quadrant multiplying digital-to-analog converter (DAC). An advanced silicon gate CMOS process combines 10 bit linearity, low power consumption, and excellent long term stability. Thin-film resistors provide 1.4% untrimmed gain error and less than 0.1% gain change with temperature over all operating ranges.

The device operates from a single +5V to +15V supply. All digital inputs are compatible with both CMOS and TTL logic levels.

Maxim's MX7533 is pin and functionally compatible with Analog Devices' AD7533 as well as the AD7520. It is packaged in 16-lead DIP and small outline packages.

Applications

Machine and Motion Control Systems

Automatic Test Equipment

µP Controlled Calibration Circuitry

Programmable Gain Amplifiers

Digitally Controlled Filters

Programmable Power Supplies

Typical Operating Circuit



Features

- 10 Bit Resolution
- ♦ 8, 9, and 10 Bit End Point Linearity
- Low Power Consumption 20mW
- Four-Quadrant Multiplication
- TTL and CMOS Compatible
- Pin-For-Pin Second Source

Ordering Information

PART	TEMP. RANGE	PACKAGE*	ERROR
MX7533JN	0°C to +70°C	Plastic DIP	0.2%
MX7533KN	0°C to +70°C	Plastic DIP	0.1%
MX7533LN	0°C to +70°C	Plastic DIP	0.05%
MX7533JCWE	0°C to +70°C	Small Outline	0.2%
MX7533KCWE	0°C to +70°C	Small Outline	0.1%
MX7533LCWE	0°C to +70°C	Small Outline	0.05%
MX7533J/D	0°C to +70°C	Dice	0.2%
MX7533AQ	-25°C to +85°C	CERDIP**	0.2%
MX7533BQ	-25°C to +85°C	CERDIP**	0.1%
MX7533CQ	-25°C to +85°C	CERDIP**	0.05%
MX7533AD	-25°C to +85°C	Ceramic	0.2%
MX7533BD	-25°C to +85°C	Ceramic	0.1%
MX7533CD	-25°C to +85°C	Ceramic	0.05%
MX7533SQ	-55°C to +125°C	CERDIP**	0.2%
MX7533TQ	-55°C to +125°C	CERDIP**	0.1%
MX7533UQ	-55°C to +125°C	CERDIP**	0.05%
MX7533SD	-55° C to +125° C	Ceramic	0.2%
MX7533TD	-55°C to +125°C	Ceramic	0.1%
MX7533UD	-55°C to +125°C	Ceramic	0.05%

All devices — 16 lead packages.

Maxim reserves the right to ship Ceramic packages in lieu of CERDIP packages.

Pin Configuration



For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maximintegrated.com.

ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND
V _{REF} to GND ±25V
R _{FB} to GND
Digital Input Voltage to GND
Output Voltage (OUT1, OUT2) (Note 1)
Power Dissipation
Plastic DIP (Derate 8.3mW/°C above +70°C) 670mW
Ceramic, CERDIP, Small Outline
(Derate 6mW/° C above +75° C) 450mW

Operating Temperature Range
Commercial J/K/L 0° C to +70° C
Industrial A/B/C25° C to +85° C
Military S/T/U
Storage Temperature
Lead Temperature (Soldering 10 secs) +300° C

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(T_A = T_{MIN} to T_{MAX}, V_{DD} = +15V, V_{REF} = +10V, V_{OUT1} = V_{OUT2} = GND, unless otherwise specified)

PARAMETER	METER SYMBOL CONDITIONS				TYP.	MAX.	UNITS	
DC ACCURACY								
Resolution				10			Bits	
Relative Accuracy (Note 2)		MX7533J/A/S MX7533K/B/T MX7533L/C/U				±0.2 ±0.1 ±0.05	% FSF	
Gain Error (Note 2,3)		Digital Inputs = V _{INH}	T _A = +25°C T _{MIN} to T _{MAX}			±1.4 ±1.5	% FSF	
Power Supply Rejection (Note 4) \Gain/_V_DD	PSRR	V _{DD} = +14V to +17V	T _A = +25°C T _{MIN} to T _{MAX}			0.005 0.008	%∕%V _D	
		OUT1, Digital Inputs = V _{INL} , V _{REF} = ±10V	$Jts = V_{INL}, \qquad \begin{array}{l} T_A = +25^{\circ}C \\ T_{MIN} \text{ to } T_{MAX} \end{array}$			±50 ±200	nA	
Output Leakage Current		OUT2, Digital Inputs = V_{INH} , $V_{REF} = \pm 10V$	T _A = +25°C T _{MIN} to T _{MAX}			±50 ±200	10	
VREF Input Resistance	RREF	$T_A = +25^{\circ}C$		5	10	20	kΩ	
VREF Resistance Tempco					-300		ppm/º	
DYNAMIC PERFORMANCE								
Output Current Settling Time (Note 5)		To 0.05% of FSR, $R_L = 100\Omega$, Digital Inputs = V_{INH} to V_{INL} and V_{INL} to V_{INH} .	T _A = +25° C T _{MIN} to T _{MAX}			600 800	ns	
Feedthrough Error (Note 4)		Digital Inputs= V _{INL} , V _{REF} =±10V, 100KHz Sinewave	T _A = +25° C T _{MIN} to T _{MAX}			±0.05 ±0.1	% FSF	
		Digital Inputs = V _{INH}	OUT1 OUT2			100 35	pF	
Output Capacitance (Note 4)	COUT	Digital Inputs = V _{INL}	OUT1 OUT2			35 100		
DIGITAL INPUTS								
Logic HIGH Threshold	VINH			+2.4			V	
Logic LOW Threshold	VINL					+0.8	۷	
Input Leakage Current		Digital Inputs = 0V or V _{DD}				±1	μA	
Input Capacitance (Note 4)						5	pF	
POWER REQUIREMENTS	_							
Occurring Councils Decad		+15V ±10% for Rated Accuracy	+13.5		+16.5	v		
Operating Supply Range	V _{DD}	Accuracy Not Guaranteed (Not	+5		+16.5			
Power Supply Current	IDD	Digital Inputs = VINH or VINL				2	mA	

Note 1: V_{OUT12} may exceed the Absolute Maximum voltage rating if the current is limited to 30mA or less. Note 2: Using internal feedback resistor (R_{FB}). Full scale range (FSR) = -(V_{REF} - 1LSB) in unipolar mode. Note 3: Maximum gain change from +25°C to T_{MIN} or T_{MAX} is ±0.1% FSR. Note 4: Guaranteed by design but not 100% tested.

Note 5: Guaranteed by design and sample tested at +25°C to ensure compliance.



Detailed Description



Figure 1. MX7533 Functional Diagram

The basic MX7533 DAC circuit consists of a thin-film R-2R resistor array with CMOS current switches as shown in Figure 1. Binarily weighted currents are switched to either OUT1 or OUT2 depending on the status of each input bit. Most applications require only an output op-amp and an external reference. The V_{REF} input accepts a wide range of reference signals including fixed and time-varying voltage or current inputs.

Equivalent Circuit Analysis

Figures 2 and 3 show the equivalent circuits for the R-2R ladder when all digital inputs are LOW and HIGH respectively. The input resistance at V_{REF} is nominally 10kΩ and does not change with digital input code. The I_REF/1024 current source, which is actually the ladder termination resistor (R_T, Figure 1), results in an intentional 1-bit current loss to GND. The I_LEAKAGE current sources represent junction and surface leakage currents.

Capacitors COUT1 and COUT2 represent the switches' ON and OFF capacitances respectively. When all inputs are switched from LOW to HIGH, the capacitance at OUT1 changes from 35pF to 100pF. This capacitance is code-dependent and is a function of the number of ON switches that are connected to a specific output.



Figure 2. Equivalent DAC Circuit (All digital inputs HIGH)







Figure 4. Unipolar Binary Operation (2-Quadrant Multiplication)

Application Information

Unipolar Operation

The most common configuration for the MX7533 is shown in Figure 4. The circuit is used for unipolar binary operation and/or 2-quadrant multiplication. R1 is used for gain adjustment. If no adjustment is desired, R1 and R2 can be omitted. The code table for unipolar operation is given in Table 1. Note that the output polarity is the inverse of the reference input.

A compensation capacitor, C1, may be needed when the DAC is used with a high speed amplifier. The purpose of the capacitor is to cancel the pole formed by the DAC's output capacitance and internal feedback resistance. The correct compensation value depends on the type of op-amp used but typically ranges from 10 to 33pF.

The output op-amp's offset voltage can degrade DAC linearity by causing OUT1 to be terminated at a non-zero voltage. The resulting linearity error is typically $2/3V_{OS}$. For best performance, a low-offset amplifier offset must be trimmed to typically used or the amplifier offset must be trimmed to typically used as LSB's value. The op-amp's in is current (IB) can also limit performance since IB x R_{FB} generates an offset error as well. IB should therefore be much less than the DAC's output current for 1 LSB, which is typically 1 μ A for the MX7533.

Bipolar Operation

Bipolar, or four-quadrant, operation is shown in Figure 5. A second amplifier and three matched resistors are required. R3, R4, and R5 should be matched or trimmed to 0.05% to maintain 10 bit performance. The output vs. code table is listed in Table 2. In multiplying applications, the MSB determines output polarity while the remaining bits control amplitude.

To adjust the circuit, load the DAC with a code of 10000 00000 and trim R1 for a 0V output. With R1 and R2 omitted, an alternative zero trim is to adjust the ratio of R3 and R4 for 0V out. Full scale can be trimmed by loading the DAC with all "zeros" or all "ones" and adjusting the amplitude of V_{REF} or varying R5 until the desired positive or negative output is obtained. The op-amp recommendations made in the Unipolar Operation section apply for bipolar operation as well.

Voltage Mode (Single Supply)

The MX7533 is connected as a voltage output DAC in Figure 6. OUT1 is connected to the external reference and OUT2 is grounded. V_{REF}, now the DAC output, is a voltage source with a constant output resistance of R_{ladder} (nominally 10kΩ). In most circuits this output is buffered with an op-amp.

An advantage of voltage mode operation is single supply operation for the complete circuit, i.e. a negative reference is not required for a positive output. It is important to note that the range of the reference is restricted. The reference input (voltage at OUT1) must



Figure 5. Bipolar Operation (4-Quadrant Multiplication)

always be positive and is limited to no more than 3.5V when V_{DD} is 15V. If the reference voltage is greater than 3.5V, or V_{DD} is reduced, linearity is degraded.

Dynamic Considerations

In static or DC applications, the AC characteristics of the output amplifier are not critical. In higher speed applications, where either the reference input is an AC signal or the DAC output must quickly settle to a new programmed value, the AC parameters of the output op-amp must be considered.

Another error source in dymamic applications is parasitic coupling of signal from the V_{REF} terminal to OUT1 or OUT2. This is normally a function of board layout and package lead-to-lead capacitance. Signals can also be injected into the DAC outputs when the digital inputs are switched. This digital feedthrough is mostly dependent on circuit board layout and on-chip capacitive coupling. Layout induced feedthrough can be minimized with guard traces between digital inputs, V_{REF} , and the DAC outputs.

Table 1: Code Table — Unipolar Binary Operation

		D	GI	TAI	. 11	PL	ANALOG OUTPUT			
1	1	1	1	1	1	1	1	1	1	-V _{REF} (1 - 2 ⁻¹⁰)
1	0	0	0	0	0	0	0	0	1	-V _{REF} (½ + 2 ⁻¹⁰)
1	0	0	0	0	0	0	0	0	0	-V _{REF} /2
0	1	1	1	1	1	1	1	1	1	-V _{REF} (½ - 2 ⁻¹⁰)
0	0	0	0	0	0	0	0	0	1	-V _{REF} (2 ⁻¹⁰)
0	0	0	0	0	0	0	0	0	0	0



Figure 6. Voltage Mode Operation

Table 2: Code Table — Bipolar (Offset Binary) Operation

	•			•						-	
ſ			D	GI	TAL	. IN	IPL	т			ANALOG OUTPUT
ţ	1	1	1	1	1	1	1	1	1	1	-V _{REF} (1 - 2-9)
ł	1	0	0	0	0	0	0	0	0	1	-V _{REF} (2-9)
ł	1	0	0	0	0	0	0	0	0	0	0
ł	0	1	1	1	1	1	1	1	1	1	V _{REF} (2-9)
i	0	0	0	0	0	0	0	0	0	1	V _{REF} (1 - 2-9)
	0	0	0	0	0	0	0	0	0	0	V _{REF}





Package Information

Package Information (continued)



Package Information (continued)





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